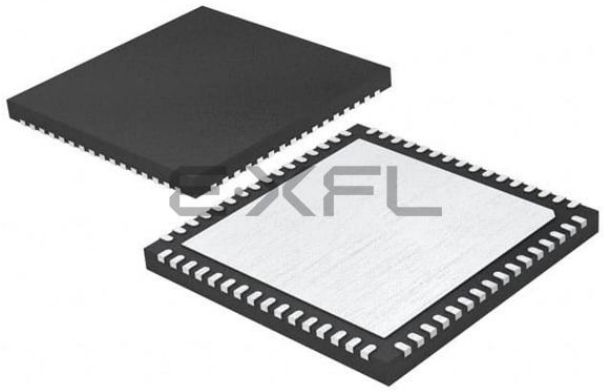
Microchip Technology - DSPIC33EV64GM106T-I/MR Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 36x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev64gm106t-i-mr

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"dsPIC33E/PIC24E Program Memory"** (DS70000613) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The dsPIC33EVXXXGM00X/10X family architecture features separate program and data memory spaces and buses. This architecture also allows the direct access of program memory from the Data Space (DS) during code execution.

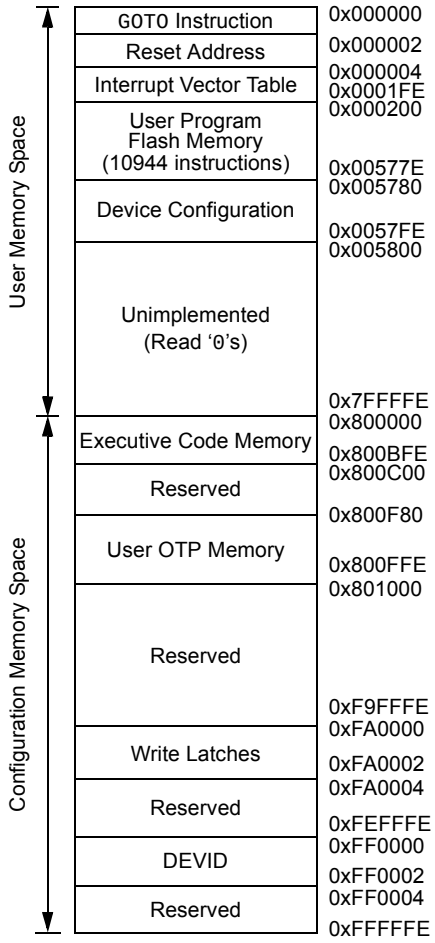
4.1 Program Address Space

The program address memory space of the dsPIC33EVXXXGM00X/10X family devices is 4M instructions. The space is addressable by a 24-bit value derived either from the 23-bit PC, during program execution or from table operation, or from DS remapping, as described in **Section 4.7 "Interfacing Program and Data Memory Spaces"**.

User application access to the program memory space is restricted to the lower half of the address range (0x000000 to 0x02ABFF). The exception is the use of the TBLRD operations, which use TBLPAG<7> to read Device ID sections of the configuration memory space and the TBLWT operations, which are used to set up the write latches located in configuration memory space.

The program memory maps, which are presented by the device family and memory size, are shown in Figure 4-1 through Figure 4-4.

FIGURE 4-1: PROGRAM MEMORY MAP FOR dsPIC33EV32GM00X/10X DEVICES(1)



Note 1: Memory areas are not shown to scale.

TABLE 4-17: PERIPHERAL INPUT REMAP REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPINR0	06A0	INT1R<7:0>								—	—	—	—	—	—	—	—	0000
RPINR1	06A2	—	—	—	—	—	—	—	—	INT2R<7:0>								0000
RPINR3	06A6	—	—	—	—	—	—	—	—	T2CKR<7:0>								0000
RPINR7	06AE	IC2R7	IC2R6	IC2R5	IC2R4	IC2R3	IC2R2	IC2R1	IC2R0	IC1R7	IC1R6	IC1R5	IC1R4	IC1R3	IC1R2	IC1R1	IC1R0	0000
RPINR8	06B0	IC4R7	IC4R6	IC4R5	IC4R4	IC4R3	IC4R2	IC4R1	IC4R0	IC3R7	IC3R6	IC3R5	IC3R4	IC3R3	IC3R2	IC3R1	IC3R0	0000
RPINR11	06B6	—	—	—	—	—	—	—	—	OCFAR<7:0>								0000
RPINR12	06B8	FLT2R7	FLT2R6	FLT2R5	FLT2R4	FLT2R3	FLT2R2	FLT2R1	FLT2R0	FLT1R7	FLT1R6	FLT1R5	FLT1R4	FLT1R3	FLT1R2	FLT1R1	FLT1R0	0000
RPINR18	06C4	—	—	—	—	—	—	—	—	U1RXR<7:0>								0000
RPINR19	06C6	—	—	—	—	—	—	—	—	U2RXR<7:0>								0000
RPINR22	06CC	SCK2R7	SCK2R6	SCK2R5	SCK2R4	SCK2R3	SCK2R2	SCK2R1	SCK2R0	SDI2R7	SDI2R6	SDI2R5	SDI2R4	SDI2R3	SDI2R2	SDI2R1	SDI2R0	0000
RPINR23	06CE	—	—	—	—	—	—	—	—	SS2R<7:0>								0000
RPINR26	06D4	—	—	—	—	—	—	—	—	C1RXR<7:0>(1)								0000
RPINR37	06EA	SYNCI1R<7:0>								—	—	—	—	—	—	—	—	0000
RPINR38	06EC	DTCMP1R<7:0>								—	—	—	—	—	—	—	—	0000
RPINR39	06EE	DTCMP3R7	DTCMP3R6	DTCMP3R5	DTCMP3R4	DTCMP3R3	DTCMP3R2	DTCMP3R1	DTCMP3R0	DTCMP2R7	DTCMP2R6	DTCMP2R5	DTCMP2R4	DTCMP2R3	DTCMP2R2	DTCMP2R1	DTCMP2R0	0000
RPINR44	06F8	SENT1R<7:0>								—	—	—	—	—	—	—	—	0000
RPINR45	06FA	—	—	—	—	—	—	—	—	SENT2R<7:0>								0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This feature is available only on dsPIC33EVXXXGM10X devices.

TABLE 4-18: DMT REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
DMTCON	0700	ON	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
DMTPRECLR	0704	STEP1<7:0>								—	—	—	—	—	—	—	—	0000
DMTCLR	0708	—	—	—	—	—	—	—	—	STEP2<7:0>								0000
DMTSTAT	070C	—	—	—	—	—	—	—	—	BAD1	BAD2	DMTEVENT	—	—	—	—	WINOPN	0000
DMTCNTL	0710	COUNTER<15:0>																0000
DMTCNTH	0712	COUNTER<31:16>																0000
DMTHOLDREG	0714	UPRCNT<15:0>																0000
DMTPSCNTL	0718	PSCNT<15:0>																0000
DMTPSCNTH	071A	PSCNT<31:16>																0000
DMTPSINTVL	071C	PSINTV<15:0>																0000
DMTPSINTVH	071E	PSINTV<31:16>																0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.5.3 MODULO ADDRESSING APPLICABILITY

Modulo Addressing can be applied to the Effective Address (EA) calculation associated with any W register. Address boundaries check for addresses equal to:

- The upper boundary addresses for incrementing buffers
- The lower boundary addresses for decrementing buffers

The address boundaries check for addresses less than or greater than the upper (for incrementing buffers) and lower (for decrementing buffers) boundary addresses (not just equal to). Address changes can, therefore, jump beyond boundaries and still be adjusted correctly.

Note:	The modulo corrected Effective Address is written back to the register only when Pre-Modify or Post-Modify Addressing mode is used to compute the Effective Address. When an address offset, such as [W7 + W2] is used, Modulo Addressing correction is performed, but the contents of the register remain unchanged.

4.6 Bit-Reversed Addressing

Bit-Reversed Addressing mode is intended to simplify data reordering for radix-2 FFT algorithms. It is supported by the X AGU for data writes only.

The modifier, which can be a constant value or register contents, is regarded as having its bit order reversed. The address source and destination are kept in normal order. Thus, the only operand requiring reversal is the modifier.

4.6.1 BIT-REVERSED ADDRESSING IMPLEMENTATION

Bit-Reversed Addressing mode is enabled when all of these conditions are met:

- BWM<3:0> bits (W register selection) in the MODCON register are any value other than '1111' (the stack cannot be accessed using Bit-Reversed Addressing)
- The BREN bit is set in the XBREV register
- The addressing mode used is Register Indirect with Pre-Increment or Post-Increment

If the length of a bit-reversed buffer is $M = 2^N$ bytes, the last 'N' bits of the data buffer start address must be zeros.

XB<14:0> is the Bit-Reversed Addressing modifier, or 'pivot point', which is typically a constant. In the case of an FFT computation, its value is equal to half of the FFT data buffer size.

Note:	All bit-reversed EA calculations assume word-sized data (LSb of every EA is always clear). The XB value is scaled accordingly to generate compatible (byte) addresses.

When enabled, Bit-Reversed Addressing is executed only for Register Indirect with Pre-Increment or Post-Increment Addressing and word-sized data writes. It does not function for any other addressing mode or for byte-sized data and normal addresses are generated instead. When Bit-Reversed Addressing is active, the W Address Pointer is always added to the address modifier (XB) and the offset associated with the Register Indirect Addressing mode is ignored. In addition, as word-sized data is a requirement, the LSb of the EA is ignored (and always clear).

Note:	Modulo Addressing and Bit-Reversed Addressing can be enabled simultaneously using the same W register, but Bit-Reversed Addressing operation will always take precedence for data writes when enabled.

If Bit-Reversed Addressing has already been enabled by setting the BREN (XBREV<15>) bit, a write to the XBREV register should not be immediately followed by an indirect read operation using the W register that has been designated as the Bit-Reversed Pointer.

The operation of Bit-Reversed Addressing is shown in Figure 4-16 and Table 4-46.

REGISTER 8-7: DMAxPAD: DMA CHANNEL x PERIPHERAL ADDRESS REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PAD<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PAD<15:0>:** DMA Peripheral Address Register bits

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

REGISTER 8-8: DMAxCNT: DMA CHANNEL x TRANSFER COUNT REGISTER(1)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	CNT<13:8>(2)					
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CNT<7:0>(2)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-0 **CNT<13:0>:** DMA Transfer Count Register bits(2)

Note 1: If the channel is enabled (i.e., active), writes to this register may result in unpredictable behavior of the DMA channel and should be avoided.

2: The number of DMA transfers = CNT<13:0> + 1.

REGISTER 9-5: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROON	—	ROSSLP	ROSEL	RODIV3(1)	RODIV2(1)	RODIV1(1)	RODIV0(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROON:** Reference Oscillator Output Enable bit
1 = Reference oscillator output is enabled on the REFCLK pin(2)
0 = Reference oscillator output is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **ROSSLP:** Reference Oscillator Run in Sleep bit
1 = Reference oscillator output continues to run in Sleep mode
0 = Reference oscillator output is disabled in Sleep mode

bit 12 **ROSEL:** Reference Oscillator Source Select bit
1 = Oscillator crystal is used as the reference clock
0 = System clock is used as the reference clock

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divider bits(1)
1111 = Reference clock divided by 32,768
1110 = Reference clock divided by 16,384
1101 = Reference clock divided by 8,192
1100 = Reference clock divided by 4,096
1011 = Reference clock divided by 2,048
1010 = Reference clock divided by 1,024
1001 = Reference clock divided by 512
1000 = Reference clock divided by 256
0111 = Reference clock divided by 128
0110 = Reference clock divided by 64
0101 = Reference clock divided by 32
0100 = Reference clock divided by 16
0011 = Reference clock divided by 8
0010 = Reference clock divided by 4
0001 = Reference clock divided by 2
0000 = Reference clock

bit 7-0 **Unimplemented:** Read as '0'

Note 1: The reference oscillator output must be disabled (ROON = 0) before writing to these bits.
2: This pin is remappable. See **Section 11.5 "Peripheral Pin Select (PPS)"** for more information.

REGISTER 11-8: RPINR18: PERIPHERAL PIN SELECT INPUT REGISTER 18

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
U1RXR<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-0 **U1RXR<7:0>:** Assign UART1 Receive (U1RX) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

REGISTER 11-9: RPINR19: PERIPHERAL PIN SELECT INPUT REGISTER 19

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
U2RXR<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7-0 **U2RXR<7:0>:** Assign UART2 Receive (U2RX) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

10110101 = Input tied to RPI181
•
•
•
00000001 = Input tied to CMP1
00000000 = Input tied to Vss

REGISTER 11-30: RPOR12: PERIPHERAL PIN SELECT OUTPUT REGISTER 12

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP180R5	RP180R4	RP180R3	RP180R2	RP180R1	RP180R0
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP179R5	RP179R4	RP179R3	RP179R2	RP179R1	RP179R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **RP180R<5:0>:** Peripheral Output Function is Assigned to RP180 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **RP179R<5:0>:** Peripheral Output Function is Assigned to RP179 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 11-31: RPOR13: PERIPHERAL PIN SELECT OUTPUT REGISTER 13

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP181R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as '0'

bit 5-0 **RP181R<5:0>:** Peripheral Output Function is Assigned to RP181 Output Pin bits (see Table 11-3 for peripheral function numbers)

12.0 TIMER1

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer that can operate as a free-running, interval timer/counter.

The Timer1 module has the following unique features over other timers:

- Can be Operated in Asynchronous Counter mode from an External Clock Source
- The Timer1 External Clock Input (T1CK) can Optionally be Synchronized to the Internal Device Clock and the Clock Synchronization is Performed after the Prescaler

A block diagram of Timer1 is shown in Figure 12-1.

The Timer1 module can operate in one of the following modes:

- Timer mode
- Gated Timer mode
- Synchronous Counter mode
- Asynchronous Counter mode

In Timer and Gated Timer modes, the input clock is derived from the internal instruction cycle clock (FCY). In Synchronous and Asynchronous Counter modes, the input clock is derived from the external clock input at the T1CK pin.

The Timer modes are determined by the following bits:

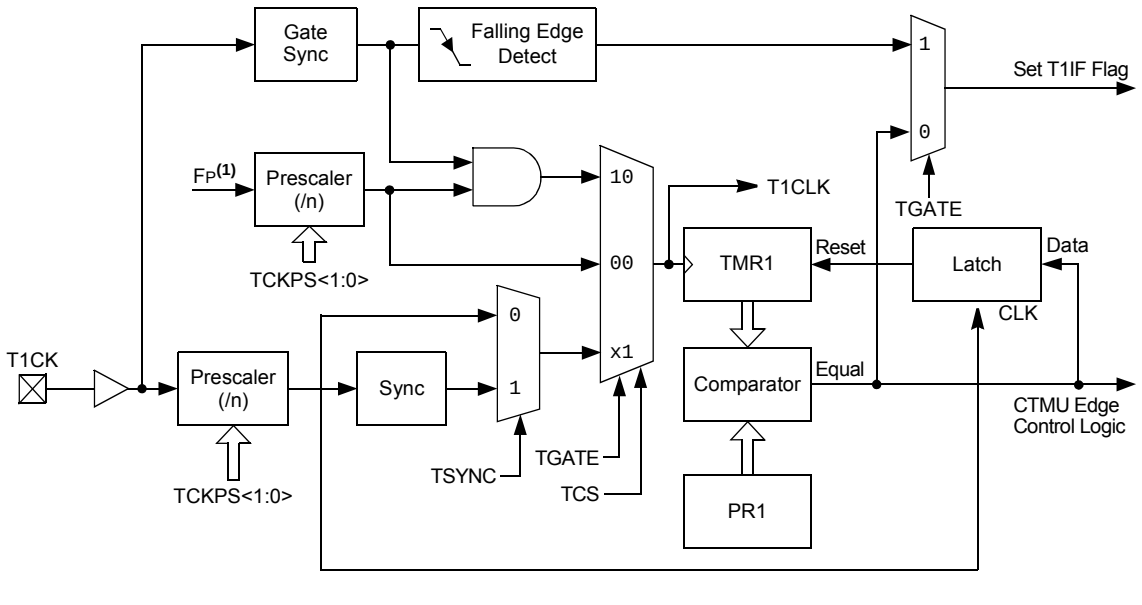
- Timer Clock Source Control bit (TCS): T1CON<1>
- Timer Synchronization Control bit (TSYNC): T1CON<2>
- Timer Gate Control bit (TGATE): T1CON<6>

Timer control bit settings for different operating modes are given in Table 12-1.

TABLE 12-1: TIMER MODE SETTINGS

Mode	TCS	TGATE	TSYNC
Timer	0	0	x
Gated Timer	0	1	x
Synchronous Counter	1	x	1
Asynchronous Counter	1	x	0

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



Note 1: FP is the peripheral clock.

REGISTER 18-2: SPIxCON1: SPIx CONTROL REGISTER 1 (CONTINUED)

bit 4-2 **SPRE<2:0>:** Secondary Prescale bits (Master mode)(3)
111 = Secondary prescale 1:1
110 = Secondary prescale 2:1
•
•
•
000 = Secondary prescale 8:1

bit 1-0 **PPRE<1:0>:** Primary Prescale bits (Master mode)(3)
11 = Primary prescale 1:1
10 = Primary prescale 4:1
01 = Primary prescale 16:1
00 = Primary prescale 64:1

Note 1: The CKE bit is not used in Framed SPI modes. Program this bit to '0' for Framed SPI modes (FRMEN = 1).

2: This bit must be cleared when FRMEN = 1.

3: Do not set both primary and secondary prescalers to the value of 1:1.

REGISTER 24-7: ADxCSSH: ADCx INPUT SCAN SELECT REGISTER HIGH(2)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS31	CSS30	CSS29	CSS28	CSS27	CSS26(1)	CSS25(1)	CSS24(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	CSS19	CSS18	CSS17	CSS16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CSS31:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 14 **CSS30:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 13 **CSS29:** ADCx Input Scan Selection bits
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 12 **CSS28:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 11 **CSS27:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 10 **CSS26:** ADCx Input Scan Selection bit(1)
1 = Selects OA3/AN6 for input scan
0 = Skips OA3/AN6 for input scan

bit 9 **CSS25:** ADCx Input Scan Selection bit(1)
1 = Selects OA2/AN0 for input scan
0 = Skips OA2/AN0 for input scan

bit 8 **CSS24:** ADCx Input Scan Selection bit(1)
1 = Selects OA1/AN3 for input scan
0 = Skips OA1/AN3 for input scan

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **CSS19:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 2 **CSS18:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

Note 1: If the op amp is selected (OPAEN bit (CMxCON<10>) = 1), the OAx input is used; otherwise, the ANx input is used.

2: All bits in this register can be selected by the user application. However, inputs selected for scan without a corresponding input on the device convert VREFL.

27.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The dsPIC33EVXXXGM00X/10X family devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

27.1 Configuration Bits

In dsPIC33EVXXXGM00X/10X family devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored at the top of the on-chip program memory space, known as the Flash Configuration bytes. Their specific locations are shown in Table 27-1. The configuration data is automatically loaded from the Flash Configuration bytes to the proper Configuration Shadow registers during device Resets.

Note: Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration bytes for configuration data in their code for the compiler. This is to ensure that program code is not stored in this address when the code is compiled.

The upper 2 bytes of all Flash Configuration Words in program memory should always be '1111 1111 1111 1111'. This makes them appear to be NOP instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '1's to these locations has no effect on device operation.

Note: Performing a page erase operation on the last page of program memory clears the Flash Configuration bytes, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

The Configuration Flash bytes map is shown in Table 27-1.

30.2 AC Characteristics and Timing Parameters

This section defines the dsPIC33EVXXXGM00X/10X family AC characteristics and timing parameters.

TABLE 30-15: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended Operating voltage VDD range as described in **Section 30.1 "DC Characteristics"**.

FIGURE 30-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

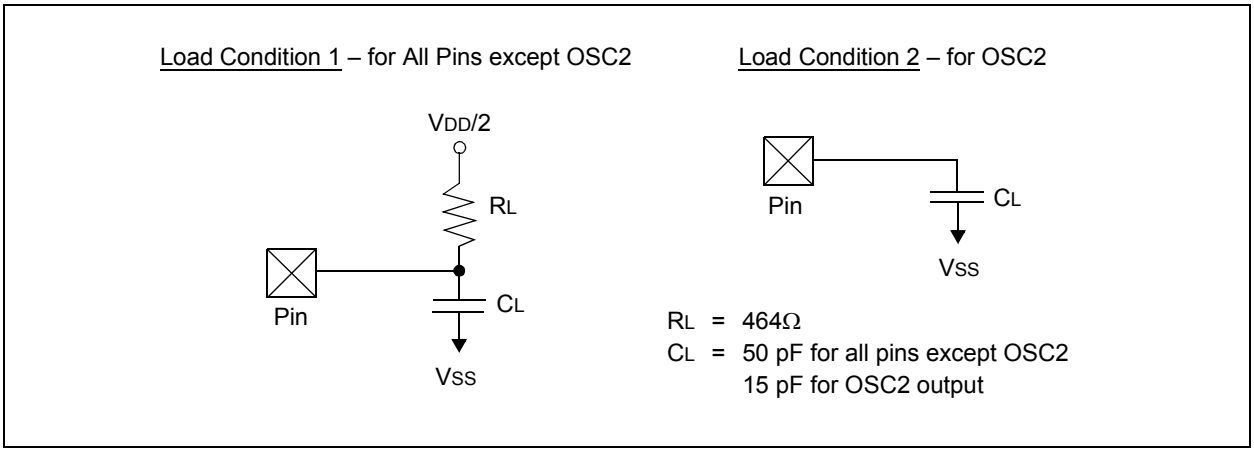
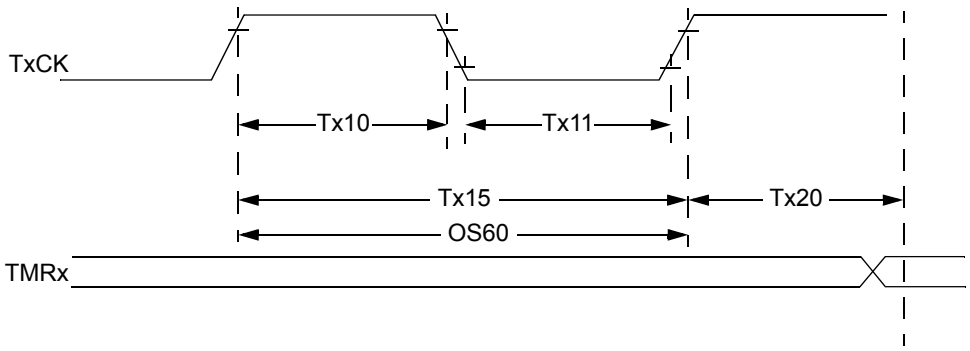


TABLE 30-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

Param No.	Symbol	Characteristic	Min.	Typ.	Max.	Units	Conditions
DO50	COSCO	OSC2 Pin	—	—	15	pF	In XT and HS modes, when external clock is used to drive OSC1
DO56	CIO	All I/O Pins and OSC2	—	—	50	pF	EC mode
DO58	CB	SCLx, SDAx	—	—	400	pF	In I^2C mode

FIGURE 30-6: TIMER1-TIMER5 EXTERNAL CLOCK TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-23: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS(1)

AC CHARACTERISTICS				Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(2)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TA10	TTXH	T1CK High Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = Prescaler Value (1, 8, 64, 256)
			Asynchronous mode	35	—	—	ns	
TA11	TTXL	T1CK Low Time	Synchronous mode	Greater of: 20 or (TCY + 20)/N	—	—	ns	Must also meet Parameter TA15, N = Prescaler Value (1, 8, 64, 256)
			Asynchronous mode	10	—	—	ns	
TA15	TTXP	T1CK Input Period	Synchronous mode	Greater of: 40 or (2 TCY + 40)/N	—	—	ns	N = Prescaler Value (1, 8, 64, 256)
OS60	Ft1	T1CK Oscillator Input Frequency Range (oscillator enabled by setting TCS (T1CON<1>) bit)		DC	—	50	kHz	
TA20	TCKEXTMRL	Delay from External T1CK Clock Edge to Timer Increment		0.75 TCY + 40	—	1.75 TCY + 40	ns	

Note 1: Timer1 is a Type A.

2: These parameters are characterized but not tested in manufacturing.

TABLE 30-42: SPI1 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP70	FscP	Maximum SCK1 Input Frequency	—	—	25	MHz	See **Note 3**
SP72	TscF	SCK1 Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCK1 Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	20	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCK1 Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	15	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SS1}$ ↓ to SCK1 ↑ or SCK1 ↓ Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SS1}$ ↑ to SDO1 Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SS1}$ ↑ after SCK1 Edge	1.5 TCY + 40	—	—	ns	See **Note 4**
SP60	TssL2doV	SDO1 Data Output Valid after $\overline{SS1}$ Edge	—	—	50	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 40 ns. Therefore, the SCK1 clock generated by the master must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

TABLE 30-51: OP AMP/COMPARATOR x VOLTAGE REFERENCE SETTLING TIME SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 2): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
VRD310	TSET	Settling Time	—	1	10	μs	See **Note 1**

Note 1: Settling time measured while CVRSS = 1 and the CVR<6:0> bits transition from '0000000' to '1111111'.

2: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

TABLE 30-52: OP AMP/COMPARATOR x VOLTAGE REFERENCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
VRD311	CVRAA	Absolute Accuracy of Internal DAC Input to Comparators	—	±25	—	mV	AVDD = CVRSRC = 5.0V
VRD312	CVRAA1	Absolute Accuracy of CVREFXO Pins	—	—	+35/-65	mV	AVDD = CVRSRC = 5.0V
VRD313	CVRSRC	Input Reference Voltage	0	—	AVDD + 0.3	V	
VRD314	CVROUT	Buffer Output Resistance	—	1.5k	—	Ω	
VRD315	CVCL	Permissible Capacitive Load (CVREFXO pins)	—	—	25	pF	
VRD316	IOCVR	Permissible Current Output (CVREFXO pins)	—	—	1	mA	
VRD317	ION	Current Consumed when Module is Enabled	—	—	500	μA	AVDD = 5.0V
VRD318	IOFF	Current Consumed when Module is Disabled	—	—	1	nA	AVDD = 5.0V

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules: ADC, op amp/comparator and comparator voltage reference, will have degraded performance. Refer to Parameter BO10 in Table 30-12 for the minimum and maximum BOR values.

TABLE 31-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
DI10	VIL	**Input Low Voltage** Any I/O Pins	VSS	—	0.2 VDD	V	
DI20	VIH	**Input High Voltage** I/O Pins	0.75 VDD	—	5.5	V	
DI30	ICNPU	**Change Notification Pull-up Current**	200	375	600	μA	VDD = 5.0V, VPIN = VSS
DI31	ICNPD	**Change Notification Pull-Down Current(7)**	175	400	625	μA	VDD = 5.0V, VPIN = VDD
DI50	IIL	**Input Leakage Current(2,3)** I/O Pins	-200	—	200	nA	VSS ≤ VPIN ≤ VDD, pin at high-impedance
DI55		MCLR	-1.5	—	1.5	μA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	-300	—	300	nA	VSS ≤ VPIN ≤ VDD, XT and HS modes
DI60a	IICL	**Input Low Injection Current**	0	—	-5(4,6)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP and RB7
DI60b	IICH	**Input High Injection Current**	0	—	+5(5,6)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, RB7 and all 5V tolerant pins(5)
DI60c	∑IICT	**Total Input Injection Current** (sum of all I/O and control pins)	-20(7)	—	+20(7)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL | + | IICH |) ≤ ∑IICT

Note 1: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: VIL source < (VSS – 0.3). Characterized but not tested.

5: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

6: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

7: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted, provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

FIGURE 32-5: TYPICAL IDD vs. VDD (EC MODE, 60 MIPS)

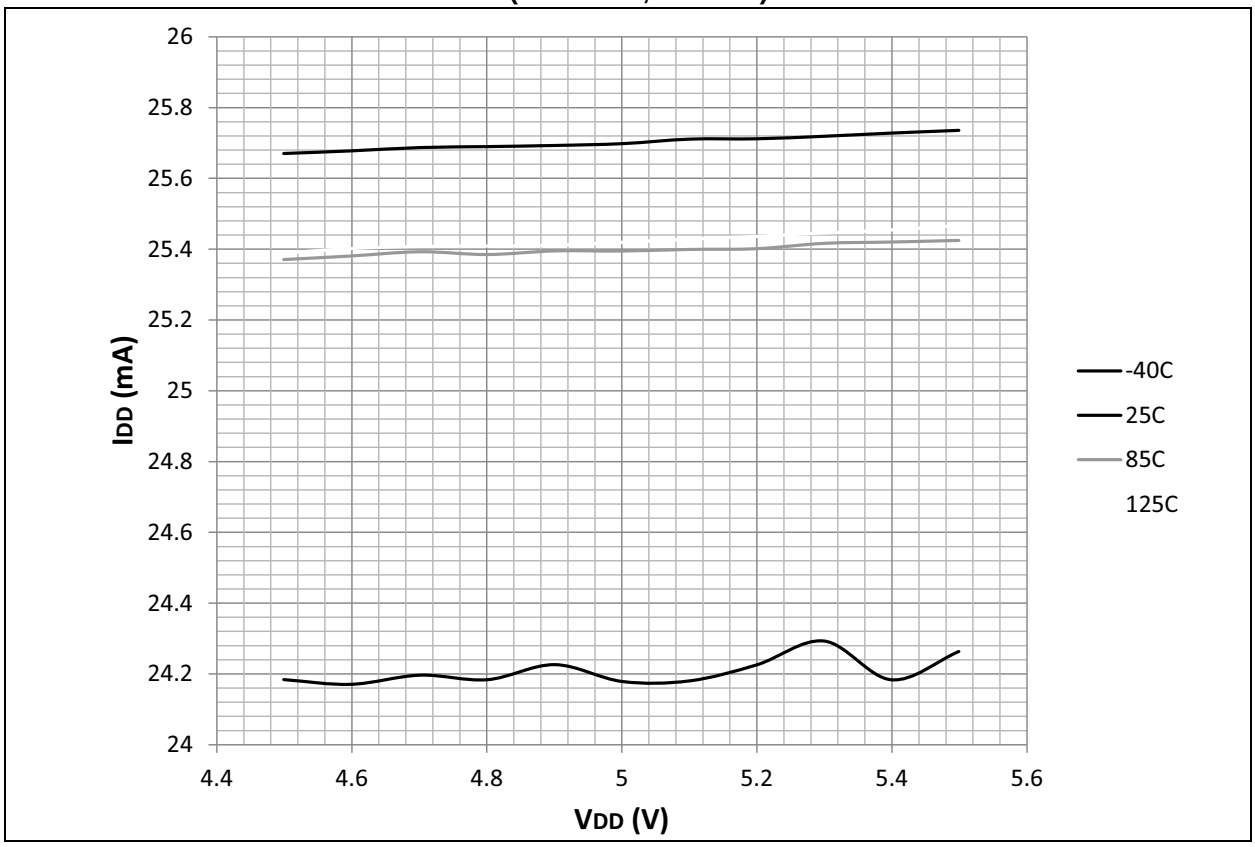
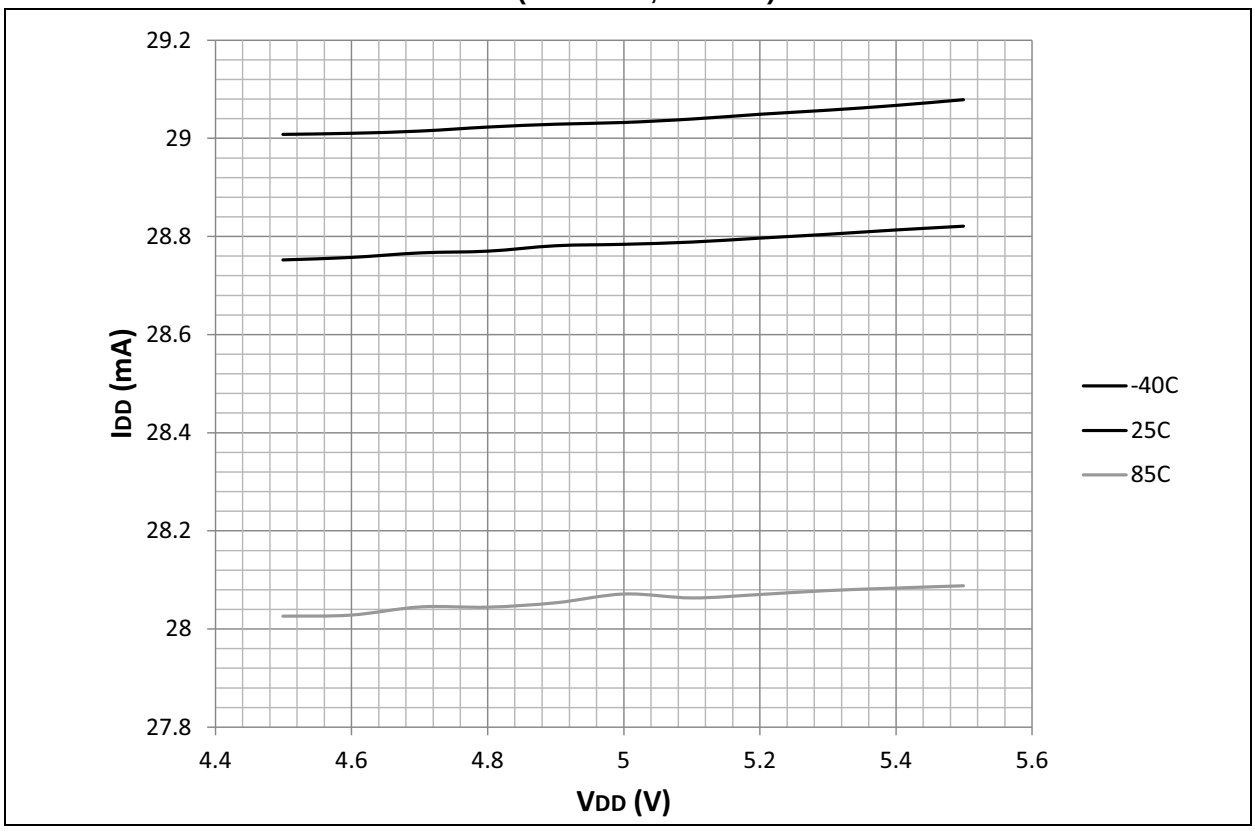
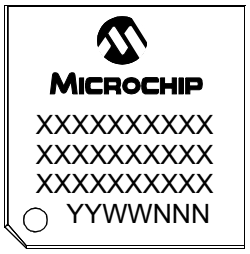


FIGURE 32-6: TYPICAL IDD vs. VDD (EC MODE, 70 MIPS)



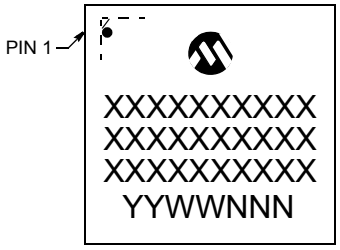
34.1 Package Marking Information (Continued)

44-Lead TQFP (10x10x1 mm)

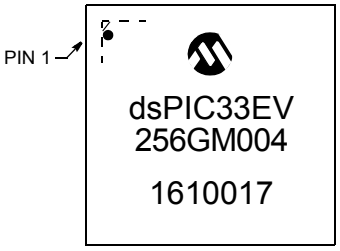


Example

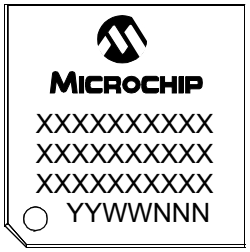
44-Lead QFN (8x8 mm)



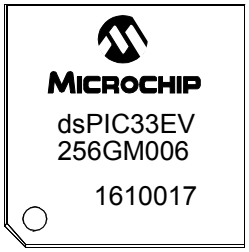
Example



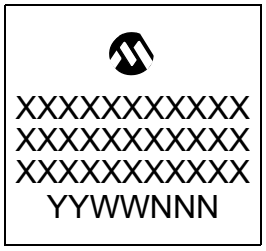
64-Lead TQFP (10x10x1 mm)



Example



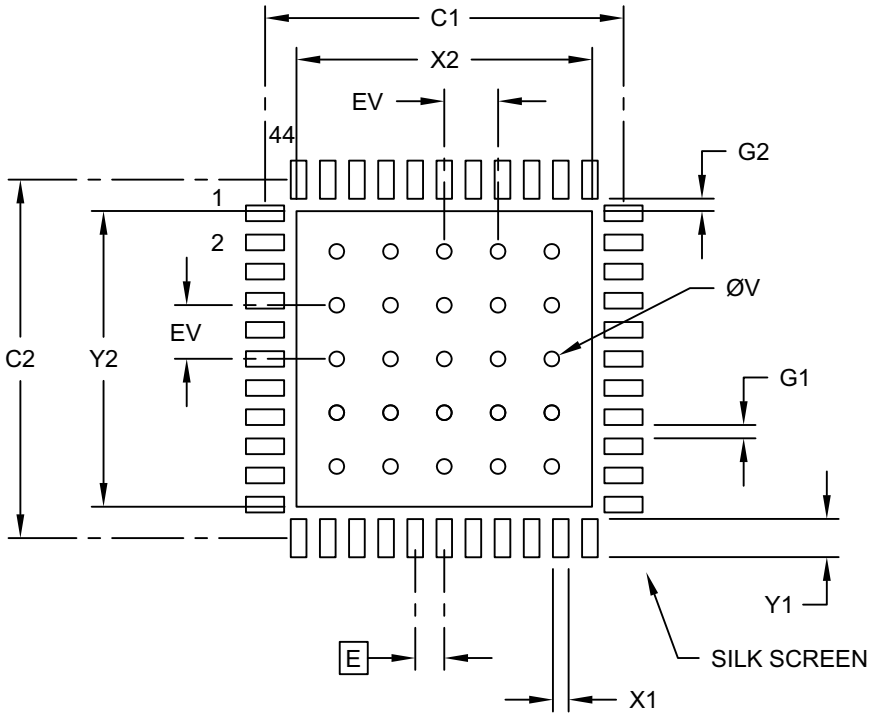
64-Lead QFN (9x9x0.9 mm)



Example

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN or VQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	X2			6.60
Optional Center Pad Length	Y2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Contact Pad to Contact Pad (X40)	G1	0.30		
Contact Pad to Center Pad (X44)	G2	0.28		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing No. C04-2103C